

**Features**

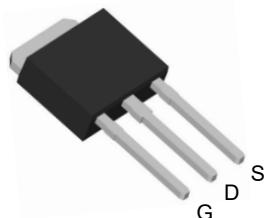
- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

**Product Summary**

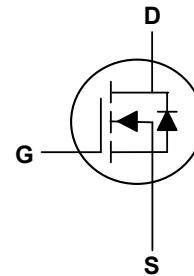
|                                  |     |    |
|----------------------------------|-----|----|
| $V_{DS}$                         | 100 | V  |
| $I_D$                            | 49  | A  |
| $R_{DS(ON)}$ (at $V_{GS}=10V$ )  | 18  | mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) | 24  | mΩ |

**Applications**

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application



TO-251A Top View

**Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)**

| Parameter                                  | Symbol                   | Rating     | Units |
|--|--------------------------|------------|-------|
| Drain-Source Voltage                       | $V_{DS}$                 | 100        | V     |
| Gate-Source Voltage                        | $V_{GS}$                 | $\pm 20$   | V     |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D @ T_c = 25^\circ C$ | 49         | A     |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D @ T_c = 70^\circ C$ | 39         | A     |
| Pulsed Drain Current <sup>2</sup>          | $I_{DM}$                 | 120        | A     |
| Single Pulse Avalanche Energy <sup>3</sup> | EAS                      | 16         | mJ    |
| Avalanche Current                          | $I_{AS}$                 | 18         | A     |
| Total Power Dissipation <sup>4</sup>       | $P_D @ T_c = 25^\circ C$ | 90         | W     |
| Storage Temperature Range                  | $T_{STG}$                | -55 to 150 | °C    |
| Operating Junction Temperature Range       | $T_J$                    | -55 to 150 | °C    |

**Thermal Characteristics**

| Parameter  | Symbol          | Typ | Max | Unit |
|--|-----------------|-----|-----|------|
| Thermal Resistance Junction-Ambient <sup>1</sup> | $R_{\theta JA}$ | --- | 62  | °C/W |
| Thermal Resistance Junction-Case <sup>1</sup>    | $R_{\theta JC}$ | --- | 1.4 | °C/W |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Parameter  | Symbol                                     | Conditions   | Min | Typ  | Max       | Unit                       |
|--|--|--|-----|------|-----------|----------------------------|
| Drain-Source Breakdown Voltage                     | $\text{BV}_{\text{DSS}}$                   | $V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$   | 100 | ---  | ---       | V                          |
| $\text{BV}_{\text{DSS}}$ Temperature Coefficient   | $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$   | --- | 0.08 | ---       | $\text{V}/^\circ\text{C}$  |
| Static Drain-Source On-Resistance <sup>2</sup>     | $R_{\text{DS}(\text{ON})}$                 | $V_{\text{GS}}=10\text{V}$ , $I_D=7\text{A}$   | --- | 16   | 18        | $\text{m}\Omega$           |
|  |  | $V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$  | --- | 20   | 24        | $\text{m}\Omega$           |
| Gate Threshold Voltage                             | $V_{\text{GS}(\text{th})}$                 | $V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$   | 1.2 | ---  | 2.5       | V                          |
| $V_{\text{GS}(\text{th})}$ Temperature Coefficient | $\Delta V_{\text{GS}(\text{th})}$          |  | --- | -5.5 | ---       | $\text{mV}/^\circ\text{C}$ |
| Drain-Source Leakage Current                       | $I_{\text{DSS}}$                           | $V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$                | --- | ---  | 10        | $\text{uA}$                |
|  |  | $V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$                | --- | ---  | 100       |                            |
| Gate-Source Leakage Current                        | $I_{\text{GSS}}$                           | $V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$                                     | --- | ---  | $\pm 100$ | nA                         |
| Forward Transconductance                           | $g_{\text{fs}}$                            | $V_{\text{DS}}=5\text{V}$ , $I_D=7\text{A}$  | --- | 24   | ---       | S                          |
| Gate Resistance                                    | $R_g$                                      | $V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$                        | --- | 1.6  | ---       | $\Omega$                   |
| Total Gate Charge                                  | $Q_g$                                      | $V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=7\text{A}$                      | --- | 36   | ---       | $\text{nC}$                |
| Gate-Source Charge                                 | $Q_{\text{gs}}$                            |  | --- | 5    | ---       |                            |
| Gate-Drain Charge                                  | $Q_{\text{gd}}$                            |  | --- | 10   | ---       |                            |
| Turn-On Delay Time                                 | $T_{\text{d}(\text{on})}$                  | $V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ ,<br>$R_G=3.3\Omega$ , $I_D=7\text{A}$ | --- | 11.5 | ---       | $\text{ns}$                |
| Rise Time  | $T_r$                                      |  | --- | 29   | ---       |                            |
| Turn-Off Delay Time                                | $T_{\text{d}(\text{off})}$                 |  | --- | 42   | ---       |                            |
| Fall Time  | $T_f$                                      |  | --- | 18   | ---       |                            |
| Input Capacitance                                  | $C_{\text{iss}}$                           | $V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$                       | --- | 1930 | ---       | $\text{pF}$                |
| Output Capacitance                                 | $C_{\text{oss}}$                           |  | --- | 245  | ---       |                            |
| Reverse Transfer Capacitance                       | $C_{\text{rss}}$                           |  | --- | 125  | ---       |                            |

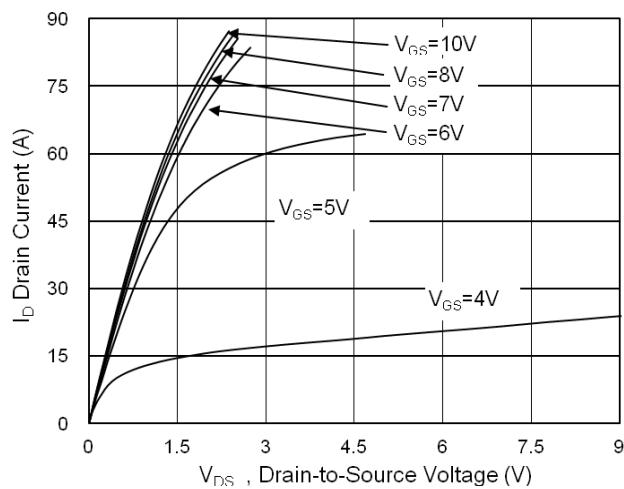
**Drain-Source Diode Characteristics**

| Parameter                                | Symbol          | Conditions  | Min | Typ | Max | Unit        |
|--|-----------------|---|-----|-----|-----|-------------|
| Continuous Source Current <sup>1,5</sup> | $I_s$           | $V_G=V_D=0\text{V}$ , Force Current   | --- | --- | 49  | A           |
| Pulsed Source Current <sup>2,5</sup>     | $I_{\text{SM}}$ |   | --- | --- | 120 | A           |
| Diode Forward Voltage <sup>2</sup>       | $V_{\text{SD}}$ | $V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$          | --- | --- | 1.2 | V           |
| Reverse Recovery Time                    | $t_{\text{rr}}$ | $I_F=7\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ ,<br>$T_J=25^\circ\text{C}$ | --- | 48  | --- | nS          |
|  | $Q_{\text{rr}}$ |   | --- | 29  | --- | $\text{nC}$ |

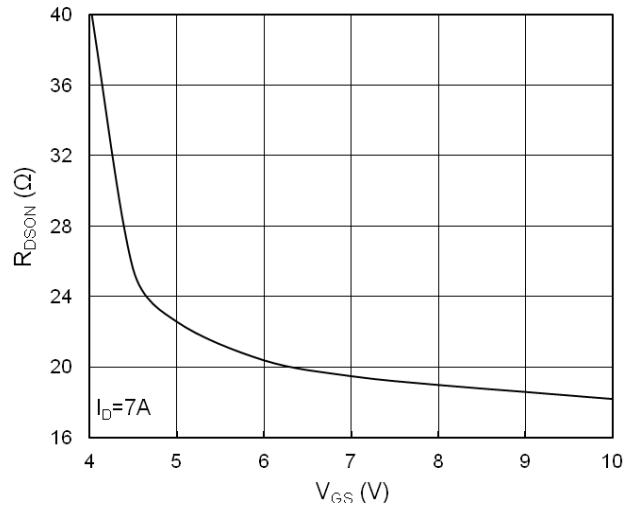
**Note:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

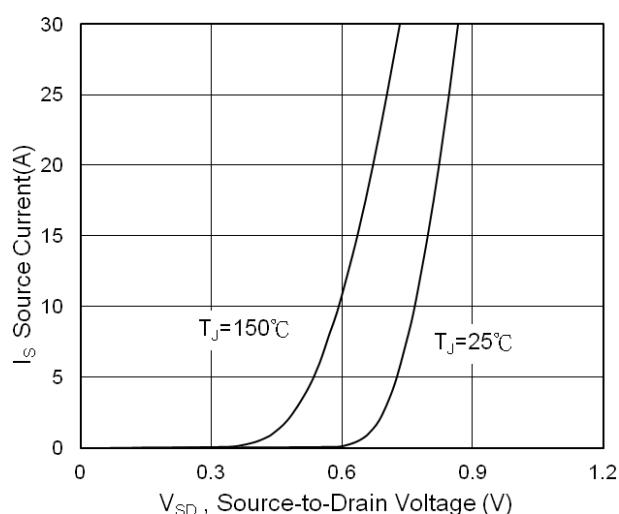
## Typical Characteristics



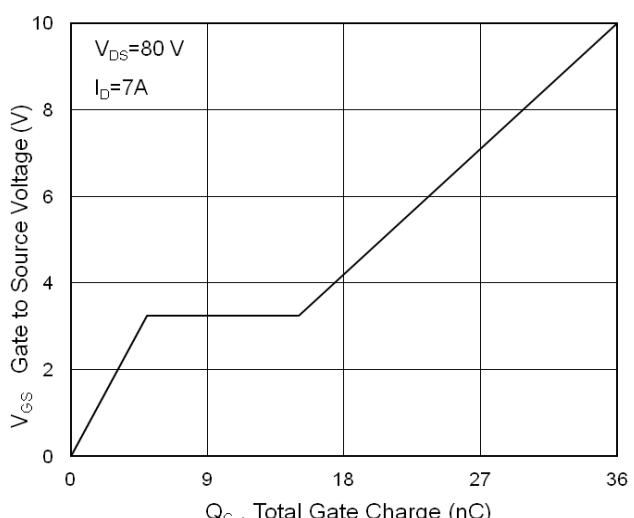
**Fig.1 Typical Output Characteristics**



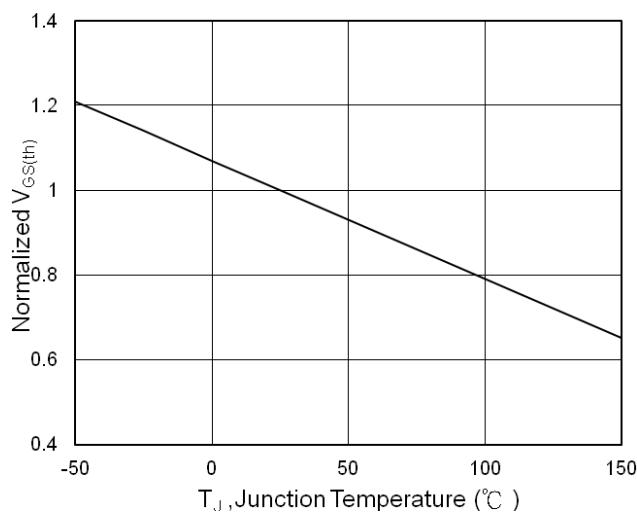
**Fig.2 On-Resistance vs. Gate-Source**



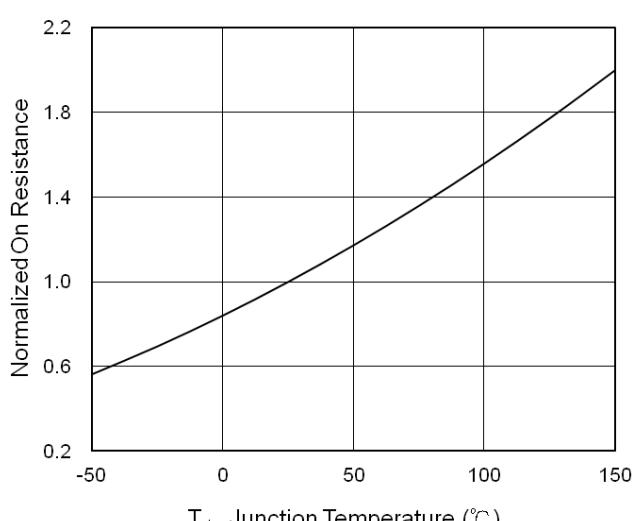
**Fig.3 Forward Characteristics Of Reverse**



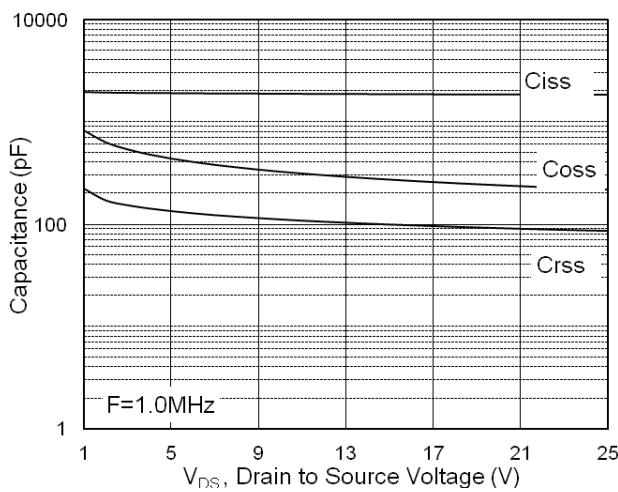
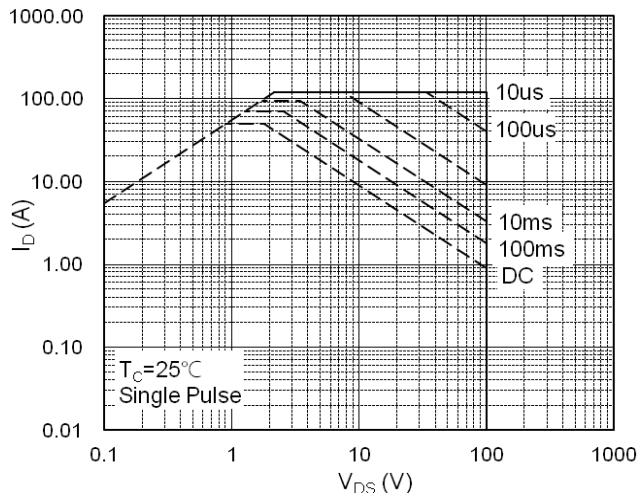
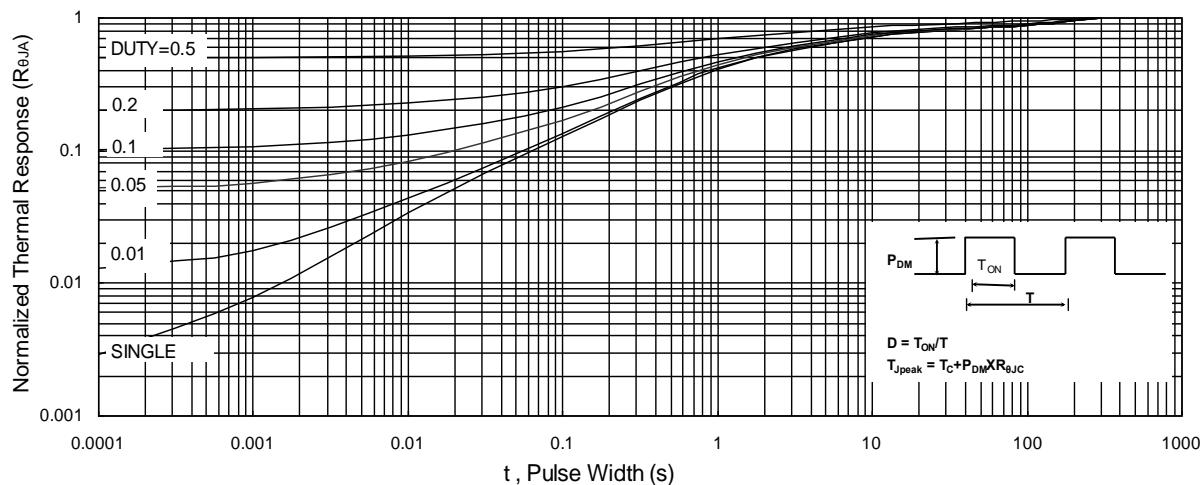
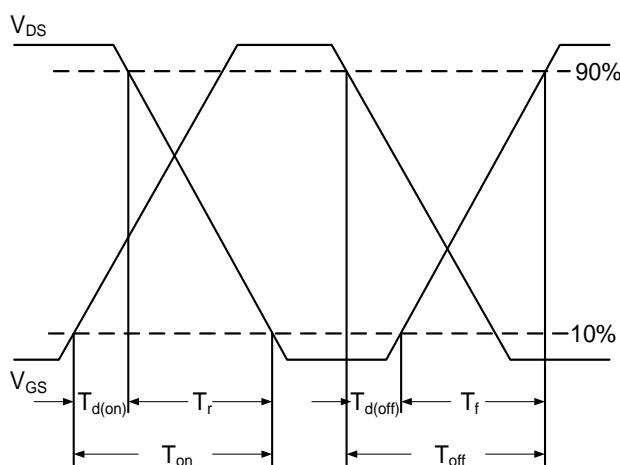
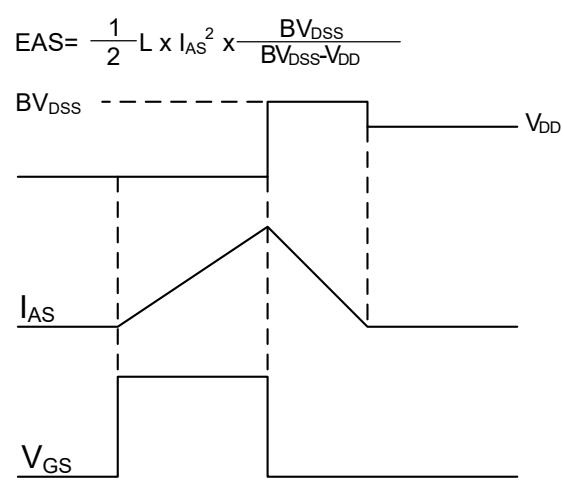
**Fig.4 Gate-Charge Characteristics**



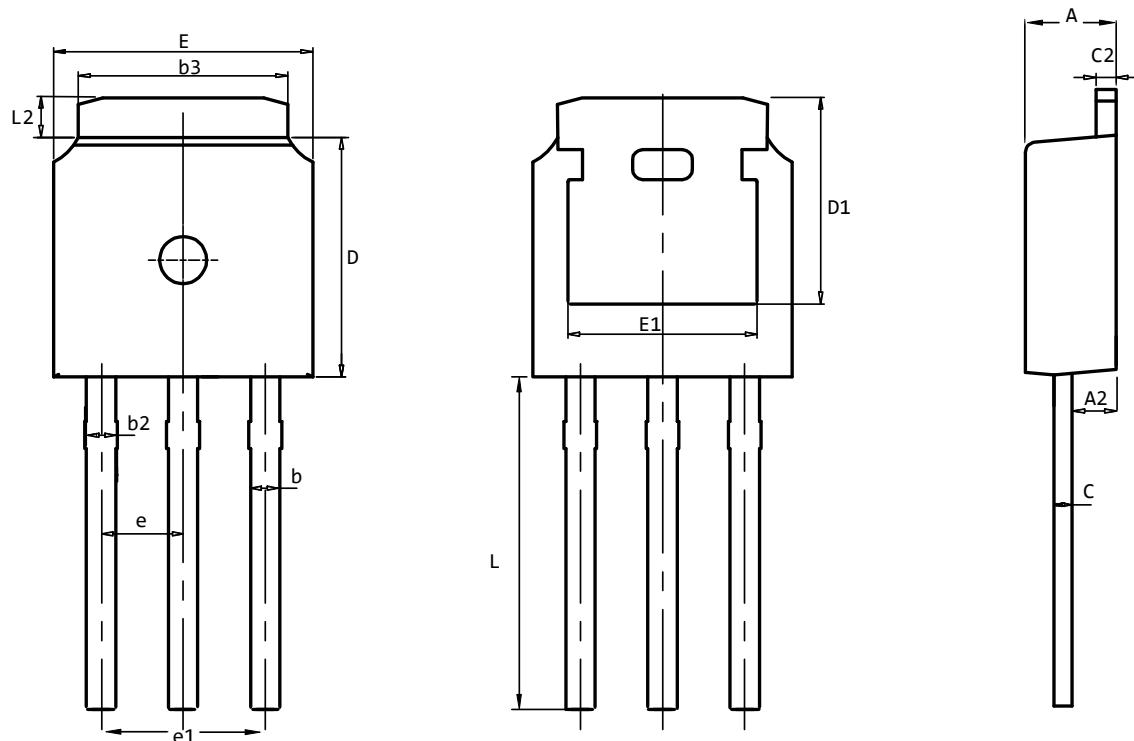
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

### TO-251A Package Outline Dimensions



| Symbol | Dimensions (unit:mm) |      |      | Symbol | Dimensions (unit:mm) |      |      |
|--------|----------------------|------|------|--------|----------------------|------|------|
|        | Min                  | Typ  | Max  |        | Min                  | Typ  | Max  |
| A      | 2.20                 | 2.30 | 2.39 | A2     | 0.90                 | 1.05 | 1.25 |
| b      | 0.60                 | 0.76 | 0.85 | b2     | 0.75                 | 0.88 | 1.15 |
| b3     | 5.10                 | 5.40 | 5.60 | C      | 0.46                 | 0.51 | 0.61 |
| C2     | 0.46                 | 0.51 | 0.61 | D      | 5.40                 | 6.10 | 6.30 |
| D1     | 5.25 REF             |      |      | E      | 6.35                 | 6.55 | 6.70 |
| E1     | 5.06 REF             |      |      | e      | 2.29 BSC             |      |      |
| e1     | 4.57 BSC             |      |      | L      | 7.50                 | 8.00 | 9.50 |
| L2     | 0.90                 | 1.06 | 1.25 |        |                      |      |      |